

SOT1901-1

WLCSP8, wafer level chip-scale package; 8 bumps; 0.810 mm x 0.505 mm x 0.23 mm body

8 March 2017

Package information

1. Package summary

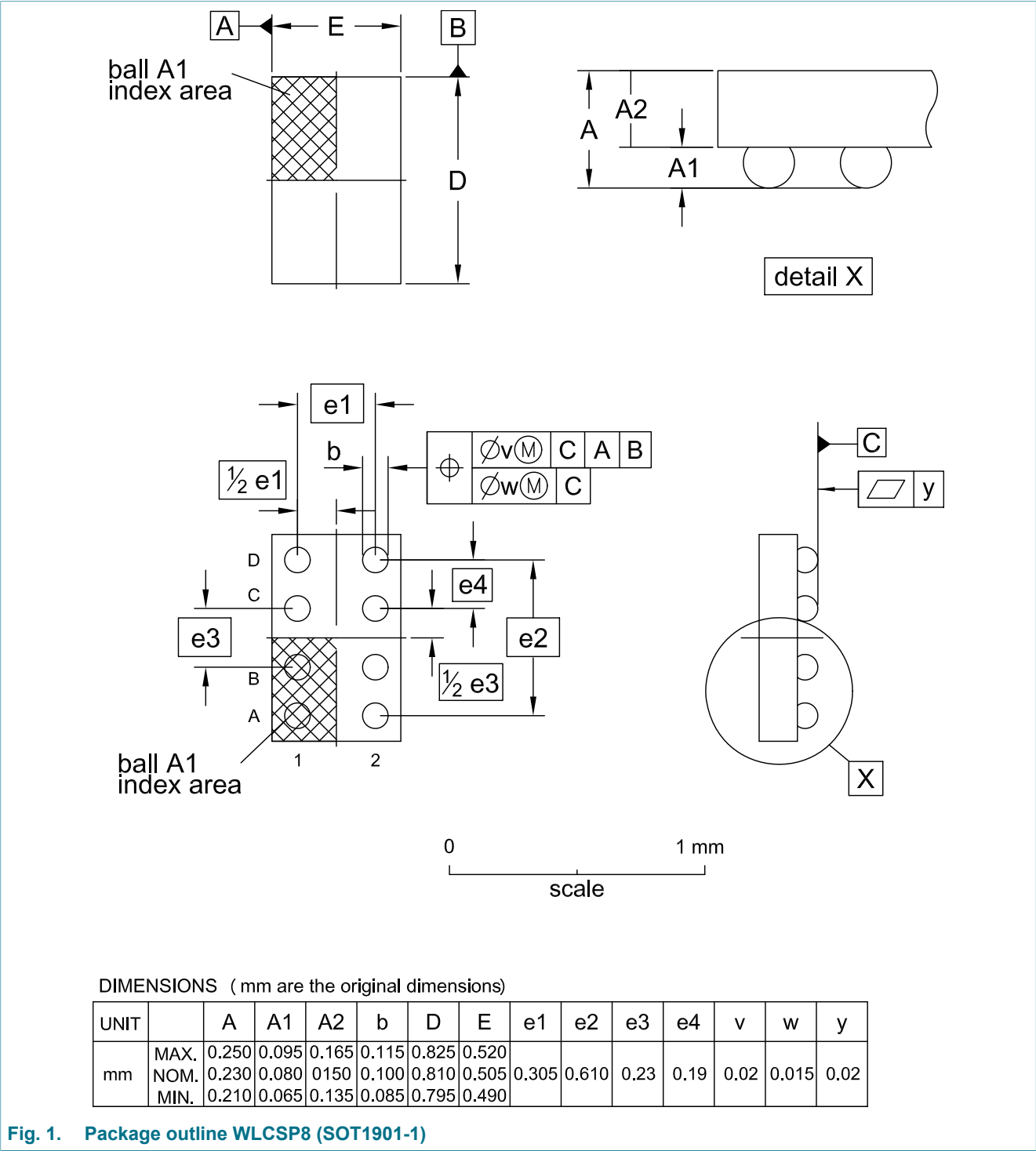
Terminal position code	B (bottom)
Package type descriptive code	WLCSP8
Package type industry code	WLCSP8
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	8-3-2017
Manufacturer package code	SOT1901-1

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		0.795	-	0.81	0.825	mm
E	package width		0.49	-	0.505	0.52	mm
A	seated height		0.21	-	0.23	0.25	mm
A ₂	package height		0.135	-	0.15	0.165	mm
e	nominal pitch		-	-	0.19	-	mm
n ₂	actual quantity of termination		-	-	8	-	



2. Package outline



3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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